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# **High Efficiency Thyristor**

1200 V  $V_{RRM}$ 

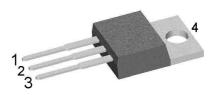
30 A

1.27 V

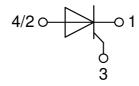
Single Thyristor

Part number

#### **CLA30E1200PB**



Backside: anode



#### Features / Advantages:

- Thyristor for line frequency
- Planar passivated chip
- Long-term stability

#### **Applications:**

- Line rectifying 50/60 Hz
- Softstart AC motor control
- DC Motor control
- Power converter
- AC power control
- Lighting and temperature control

Package: TO-220

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

#### Terms \_Conditions of usage:

The data contained in this product data sheet is exclusively intended for technically trained staff. The user will have to evaluate the suitability of the product for the intended application and the completeness of the product data with respect to his application. The specifications of our components may not be considered as an assurance of component characteristics. The information in the valid application- and assembly notes must be considered. Should you require product information in excess of the data given in this product data sheet or which concerns the specific application of your product, please contact the sales office, which is responsible for you.

Due to technical requirements our product may contain dangerous substances. For information on the types in question please contact the sales office, which is responsible for you.

Should you intend to use the product in aviation, in health or live endangering or life support applications, please notify. For any such application we urgently recommend

to perform joint risk and quality assessments;
the conclusion of quality agreements;

- to establish joint measures of an ongoing product survey, and that we may make delivery dependent on the realization of any such measures.

IXYS reserves the right to change limits, conditions and dimensions.

Data according to IEC 60747 and per semiconductor unless otherwise specified

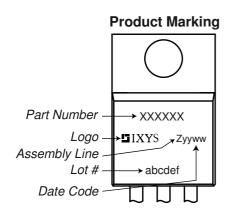
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Thyristo				l	Ratings		1
Symbol	Definition	Conditions		min.	typ.	max.	Un
V <sub>RSM/DSM</sub>	max. non-repetitive reverse/forwa		$T_{VJ} = 25^{\circ}C$			1300	
V <sub>RRM/DRM</sub>	max. repetitive reverse/forward bl	<u> </u>	$T_{VJ} = 25^{\circ}C$			1200	,
R/D	reverse current, drain current	$V_{R/D} = 1200 \text{ V}$	$T_{VJ} = 25^{\circ}C$			10	μ
		$V_{R/D} = 1200 \text{ V}$	T <sub>vJ</sub> = 125°C			2	m
V <sub>T</sub>	forward voltage drop	$I_T = 30 \text{ A}$	$T_{VJ} = 25^{\circ}C$			1.30	١
		I <sub>T</sub> = 60 A				1.59	١
		$I_{T} = 30 \text{ A}$	$T_{VJ} = 125$ °C			1.27	١
		$I_T = 60 \text{ A}$				1.65	,
I <sub>TAV</sub>	average forward current	$T_C = 115$ °C	$T_{VJ} = 150$ °C			30	1
I <sub>T(RMS)</sub>	RMS forward current	180° sine				47	1
V <sub>T0</sub>	threshold voltage		T <sub>vJ</sub> = 150°C			0.86	١
r <sub>T</sub>	slope resistance } for power lo	oss calculation only				13.2	m۵
R <sub>thJC</sub>	thermal resistance junction to cas	e				0.5	K/V
R <sub>thCH</sub>	thermal resistance case to heatsin				0.50		K/V
P <sub>tot</sub>	total power dissipation		T <sub>C</sub> = 25°C		0.00	250	٧
I <sub>TSM</sub>	max. forward surge current	t = 10 ms; (50 Hz), sine	$T_{V,I} = 45^{\circ}C$			300	,
•ISM		t = 8.3  ms; (60 Hz), sine	$V_R = 0 V$			325	,
		t = 0.0  ms; (50  Hz),  sine t = 10  ms; (50  Hz),  sine	T <sub>v.i</sub> = 150°C			255	,
		t = 8.3  ms; (60  Hz),  sine	$V_R = 0 V$			275	
l²t	value for fusing	t = 0.5  ms, (00  Hz),  sine t = 10  ms; (50  Hz),  sine	$T_{VJ} = 45^{\circ}C$			450	A <sup>2</sup>
1-(	value for fusing		$V_R = 0 V$			440	A <sup>2</sup>
		t = 8.3  ms; (60 Hz), sine t = 10  ms; (50 Hz), sine	$V_{R} = 0 V$ $T_{V,I} = 150 ^{\circ}C$				į
			• •			325	A2
•	i un akin un anna aikan an	t = 8,3 ms; (60 Hz), sine	$V_R = 0 V$		40	315	A <sup>2</sup>
C <sub>J</sub>	junction capacitance	$V_R = 400 V f = 1 MHz$	$T_{VJ} = 25^{\circ}C$		13		pl
$P_{GM}$	max. gate power dissipation	$t_P = 30 \mu s$	$T_{C} = 150^{\circ}C$			10	۷
		t <sub>P</sub> = 300 μs				5	٧
P <sub>GAV</sub>	average gate power dissipation					0.5	٧
(di/dt) <sub>cr</sub>	critical rate of rise of current		epetitive, $I_T = 90 A$			150	A/µ
		$t_P = 200 \mu s; di_G/dt = 0.3 A/\mu s; -$					1
		$I_G = 0.3 A; V = \frac{2}{3} V_{DRM}$ no	on-repet., $I_T = 30 A$			500	A/μ
$(dv/dt)_{cr}$	critical rate of rise of voltage	$V = \frac{2}{3} V_{DRM}$	$T_{VJ} = 150$ °C			500	V/µ
		R <sub>GK</sub> = ∞; method 1 (linear volta	ge rise)				
V <sub>GT</sub>	gate trigger voltage	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			1.3	١
			$T_{vJ} = -40$ °C			1.6	١
I <sub>GT</sub>	gate trigger current	$V_D = 6 V$	$T_{VJ} = 25^{\circ}C$			30	m
			$T_{VJ} = -40$ °C			50	m/
V <sub>GD</sub>	gate non-trigger voltage	$V_D = \frac{2}{3} V_{DBM}$	T <sub>vJ</sub> = 150°C			0.2	١
I <sub>GD</sub>	gate non-trigger current	5 5				1	m/
I <sub>L</sub>	latching current	t <sub>n</sub> = 10 μs	T <sub>vJ</sub> = 25°C			90	m
•∟	3	$I_{\rm G} = 0.3  \text{A};  \text{di}_{\rm G}/\text{dt} = 0.3  \text{A}/\mu \text{s}$					
I <sub>H</sub>	holding current	$V_D = 6 \text{ V } R_{GK} = \infty$	$T_{VJ} = 25$ °C			60	m/
	gate controlled delay time	$V_D = \frac{1}{2} V_{DRM}$	$T_{VJ} = 25 ^{\circ}\text{C}$			2	Î
t <sub>gd</sub>	gate controlled delay tille					2	μ
	turn off time-	$I_{\rm G} = 0.3  \text{A};  \text{di}_{\rm G}/\text{dt} = 0.3  \text{A}/\mu \text{s}$			150		-
t <sub>q</sub>	turn-off time	$V_R = 100 \text{ V}; I_T = 30 \text{ A}; V = \frac{2}{7}$			150		μ
		$di/dt = 10 A/\mu s dv/dt = 20 V$	/ $\mu s t_p = 200  \mu s$				į



Package TO-220			Ratings			
Symbol	Definition	Conditions	min.	typ.	max.	Unit
I <sub>RMS</sub>	RMS current	per terminal			35	Α
T <sub>VJ</sub>	virtual junction temperature		-40		150	°C
T <sub>op</sub>	operation temperature		-40		125	°C
T <sub>stg</sub>	storage temperature		-40		150	°C
Weight				2		g
M <sub>D</sub>	mounting torque		0.4		0.6	Nm
F <sub>c</sub>	mounting force with clip		20		60	Ν



### Part description

C = Thyristor(SCR)

L = High Efficiency Thyristor

A = (up to 1200V)

30 = Current Rating [A]

E = Single Thyristor

1200 = Reverse Voltage [V] PB = TO-220AB (3)

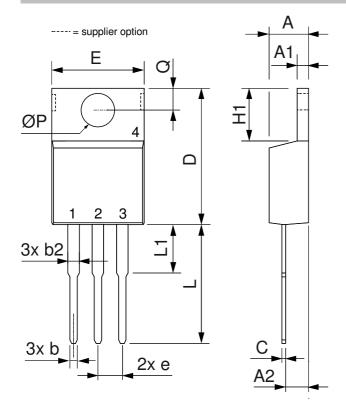
Ordering	Ordering Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	CLA30E1200PB	CLA30E1200PB	Tube	50	508228

Similar Part	Package	Voltage class
CLA30E1200HB	TO-247AD (3)	1200
CLA30E1200PC	TO-263AB (D2Pak) (2)	1200
CS22-12io1M	TO-220ABFP (3)	1200
CS22-08io1M	TO-220ABFP (3)	800
CMA30E1600PN	TO-220ABFP (3)	1600
CMA30E1600PB	TO-220AB (3)	1600
CMA30E1600PZ	TO-263AB (D2Pak) (2HV)	1600

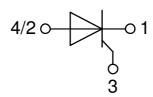
Equiva	alent Circuits for	Simulation	* on die level	$T_{VJ} = 150 ^{\circ}\text{C}$
$I \rightarrow V_0$	)—[R <sub>0</sub> ]-	Thyristor		
V <sub>0 max</sub>	threshold voltage	0.86		V
$R_{0 \text{ max}}$	slope resistance *	10		$m\Omega$



### Outlines TO-220



Dim.	Millimeter		Inches		
	Min.	Max.	Min.	Max.	
Α	4.32	4.82	0.170	0.190	
A1	1.14	1.39	0.045	0.055	
A2	2.29	2.79	0.090	0.110	
b	0.64	1.01	0.025	0.040	
b2	1.15	1.65	0.045	0.065	
С	0.35	0.56	0.014	0.022	
D	14.73	16.00	0.580	0.630	
E	9.91	10.66	0.390	0.420	
е	2.54	BSC	0.100	BSC	
H1	5.85	6.85	0.230	0.270	
L	12.70	13.97	0.500	0.550	
L1	2.79	5.84	0.110	0.230	
ØP	3.54	4.08	0.139	0.161	
Q	2.54	3.18	0.100	0.125	





### **Thyristor**

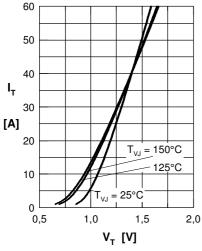


Fig. 1 Forward characteristics

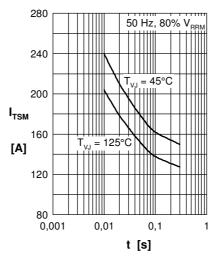


Fig. 2 Surge overload current  $I_{TSM}$ : crest value, t: duration

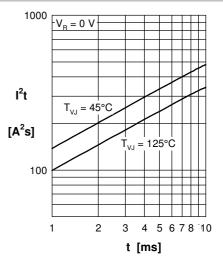


Fig. 3 I<sup>2</sup>t versus time (1-10 s)

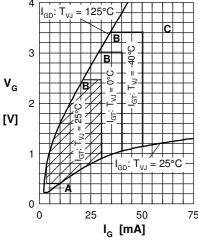


Fig. 4 Gate voltage & gate current Triggering: A = no; B = possible; C = safe

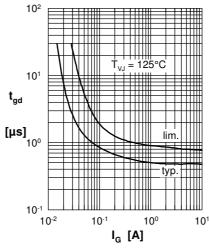


Fig. 5 Gate controlled delay time  $t_{qd}$ 

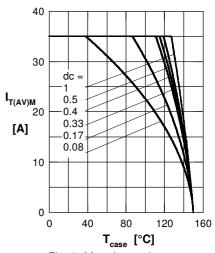


Fig. 6 Max. forward current at case temperature

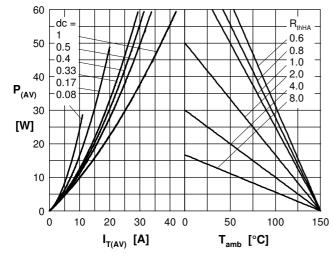


Fig. 7a Power dissipation versus direct output current Fig. 7b and ambient temperature

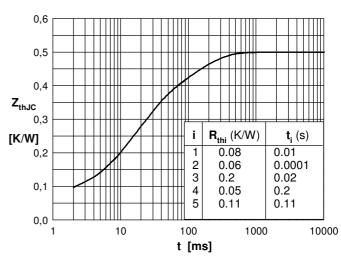


Fig. 7 Transient thermal impedance junction to case